

APPARATUS FOR MANUFACTURING SEMICONDUCTOR WAFERS

CROSS-REFERENCE TO RELATED APPLICATION

This application claims the priority benefit of China application serial no. 201110441994.7, filed Dec. 26, 2011. All disclosure of the China application is incorporated herein by reference.

FIELD OF THE INVENTION

The present invention relates to the field of semiconductor manufacturing technology, and more particularly to an apparatus for manufacturing semiconductor wafers.

BACKGROUND OF THE INVENTION

In a conventional apparatus for manufacturing semiconductor wafers, the air circulating and filtering unit of the apparatus utilizes a single control electric motor to control the air flow and the pressure in the whole apparatus, thus the internal of the apparatus may not reach a high cleaning degree. Furthermore, since the apparatus generally utilizes a single-armed manipulator which processes only one wafer at a time with less degree of freedom and small covering area, the wafer transport efficiency is low. In addition, due to the uneven distribution of the chemical gas distribution unit in the apparatus, the flow and pressure in each process chamber is different, which affects the product yield rate per unit area.

SUMMARY OF THE INVENTION

Accordingly, at least one objective of the present invention is to provide an apparatus for manufacturing semiconductor wafers to improve the cleaning degree in the inner of the apparatus, and enhance the wafer transport efficiency as well as the product yield per unit area.

To achieve these and other advantages and in accordance with the objective of the invention, as embodied and broadly described herein, the invention provides an apparatus for manufacturing semiconductor wafers, comprising at least two manipulators, at least one set of chemical gas distribution unit and an air circulating and filtering unit, wherein, the air circulating and filtering unit comprises multiple control electric motors for achieving uniform air flow and uniform pressure in the respective regions controlled thereby.

According to the concept of the present invention, the manipulator is a double-armed manipulator having multiple degrees of freedom.

According to the concept of the present invention, the manipulators comprises a wafer access manipulator for placing a processed wafer picked up from the process unit into a storing and adjusting unit, meanwhile placing the unprocessed wafer into the process unit for processing.

According to the concept of the present invention, the components in the internal of the chemical gas distribution unit are symmetrically positioned.

According to the concept of the present invention, the apparatus for manufacturing semiconductor wafers further comprises multiple static eliminators covering the transport region of the wafers respectively.

According to the concept of the present invention, the multiple process chambers are symmetrically arranged in lines.

According to the concept of the present invention, the apparatus for manufacturing semiconductor wafers further comprises multiple valve module units symmetrically disposed on the side of the apparatus.

In the present invention, the cleaning degree in the internal of the apparatus for manufacturing semiconductor can be improved through regional control by the air circulating and filtering unit, the wafer transport efficiency can be enhanced by utilizing the double-armed manipulator having multiple degrees of freedom, and the product yield per unit area can be increased by the chemical gas distribution unit providing stable and uniform flow and pressure.

BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings are included to provide a further understanding of the invention, and are incorporated in and constitute a part of this specification. The drawings illustrate embodiments of the invention and, together with the description, serve to explain the principles of the invention.

Fig. 1 is a view of the apparatus for manufacturing semiconductor wafer in one embodiment of the present invention;

Fig. 2 is a top view of the external of the apparatus for manufacturing semiconductor wafer in one embodiment of the present invention;

Fig. 3 is a top view of the internal of the apparatus for manufacturing semiconductor wafer in one embodiment of the present invention.

DETAILED DESCRIPTION OF THE EMBODIMENTS

An apparatus for manufacturing semiconductor wafer will be described in further details hereinafter with respect to the embodiment of the present invention and the accompanying drawings.

Reference will now be made in detail to the present preferred embodiments of the invention, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers are used in the drawings and the description to refer to the same or like parts.

Fig.1 illustrates an apparatus for manufacturing semiconductor wafers according to an embodiment of the present invention. The apparatus comprises at least two manipulators for transporting the wafers, at least a set of chemical gas distribution units 2 and an air circulating and filtering unit 3.

The air circulating and filtering unit 3 comprises a plurality of control electric motors to achieve the airflow uniformity and the pressure uniformity in the regions controlled thereby. Referring to Fig. 2 of the drawings, the air circulating and filtering unit 3 is separated into three regions, including the front region, the middle region, and the side region. The two small parts in the front region are controlled by an electric motor to achieve uniform air flow and uniform pressure in the front region; the two small parts in the middle region are controlled by another electric motor to achieve uniform air flow and uniform pressure in the middle region; the eight small parts in the side region are controlled by eight independent electric motors respectively to achieve uniform air flow and uniform pressure in each small part of the side region. In general, the pressure in the side region is higher than that in the middle region, and the pressure in the middle region is higher than that in the front region. The manipulators are double-armed manipulators having multiple degrees of freedom. In an embodiment, each manipulator 1 comprises a wafer access manipulator 4 for transporting the wafer in the transport region. The manipulator 4 is used for placing the processed wafers picked up from the process unit 5 into the storing and adjusting unit 6, meanwhile placing the unprocessed wafers picked up from the storing and adjusting unit 6 into the process unit 5.

The components in the internal of the chemical gas distribution unit 2 are arranged symmetrically. The apparatus also comprises a plurality of static eliminators 7 covering the transport region of the wafers respectively. The process chambers 8 of the apparatus are symmetrically arranged in lines.

In addition, the apparatus for manufacturing semiconductor wafers further comprises multiple valve module units 9. The valve module units 9 are symmetrically arranged on the side of the

apparatus and below the process chambers 8.

The operation process of the apparatus for manufacturing semiconductor wafers of an embodiment of the present invention will be described as follows in further details:

In the initial operation of the apparatus, the wafer loading port 10 of the apparatus receives wafer cassettes 11 from the factory; the manipulator 1 picks up the wafer from the wafer cassette 11, and transports the wafer into the storing and adjusting unit 6 for rotating to adjust the position of the wafer and reading the wafer code; then the wafer access manipulator 4 picks up the wafer in the storing and adjusting unit 6 and transports the wafer to the process chamber 8; when the process is complete, the wafer access manipulator 4 picks up the processed wafer from the process chamber 8 and transports it to the storing and adjusting unit 6, meanwhile picks up the unprocessed wafer in the storing and adjusting unit 6 and transports it to the process chamber; the manipulator 1 picks up the former processed wafer in the storing and adjusting unit 6 and transports it into the wafer cassette 11, meanwhile picks up another wafer in the wafer cassette 11 and transports it into the storing and adjusting unit 6 for rotating to adjust the position and code reading. The process mentioned above can be repeated.

In the stable operation, the wafer access manipulator 4 picks up the processed wafer from the process chamber 8, and then transports another unprocessed wafer into the process chamber 8. Since the wafer access manipulator 4 is a double-armed manipulator, it can clamp two wafers at a same time. When the wafer access manipulator 4 moves to the process chamber 8 with one hand empty and the other hand clamping the unprocessed wafer, the empty hand will pick up the processed wafer from the process chamber 8 and the other hand will subsequently transport the unprocessed wafer into the process chamber 8.

Referring to Fig.3, eight process chambers 8 with the same function are provided. Specifically, the wafer access manipulator 4 can transport the unprocessed wafer to a nearest process chamber 8 or to a process chamber 8 already having a processed wafer therein. In the latter case, the wafer access manipulator 4 first picks up the processed wafer and then places the unprocessed wafer into the process chamber 8.

Referring to Fig.1, two storing and adjusting units 6 with the same function are provided. Each of the storing and adjusting units 6 comprises an upper layer and a bottom layer for storing two wafers. The upper layer stores the processed wafer and performs the function of transferring; the bottom layer stores the unprocessed wafer and performs the function of transferring, rotating and position adjusting, and code reading.

During the operation of the apparatus, the air circulating and filtering unit 3 and the static eliminators 7 function all the time; wherein the air circulating and filtering unit 3 outputs vertical laminar flow from up to down, the static eliminators 7 output vertical plasma flow from up to down.

In summary, in the present invention, the apparatus for manufacturing semiconductor wafer utilizes the air circulating and filtering unit to perform regional control to improve the cleaning degree in the internal of the apparatus; in addition, the apparatus utilizes double-armed manipulators having multiple degrees of freedom to enhance the wafer transport efficiency; furthermore, the chemical gas distribution unit of the apparatus providing stable and uniform flow and pressure increases the product yield per unit area which provides industrial application.

Although the present invention has been disclosed as above with respect to the preferred embodiments, they should not be construed as limitations to the present invention. Various modifications and variations can be made by the ordinary skilled in the art without departing the spirit and scope of the present invention. Therefore, the protection scope of the present invention should be defined by the appended claims.

CLAIMS:

1. An apparatus for manufacturing semiconductor wafers, comprising:
at least two manipulators;
at least one set of chemical gas distribution unit; and
an air circulating and filtering unit, wherein the air circulating and filtering unit comprises multiple control electric motors for achieving uniform air flow and uniform pressure in the regions controlled thereby respectively.
2. The apparatus according to claim 1, wherein the manipulator is a double-armed manipulator having multiple degrees of freedom.
3. The apparatus according to claim 2, wherein the manipulators comprises a wafer access manipulator for placing a processed wafer picked up from the process unit into the storing and adjusting unit, meanwhile placing an unprocessed wafer into the process unit for processing.
4. The apparatus according to claim 1, wherein the components in the internal of the chemical gas distribution unit are symmetrically positioned.
5. The apparatus according to claim 3, wherein further comprising multiple static eliminators covering the transport region of the wafers respectively.
6. The apparatus according to claim 3, the multiple process chambers are symmetrically arranged in lines.
7. The apparatus according to claim 6, further comprising multiple valve module units symmetrically disposed on the side of the apparatus.